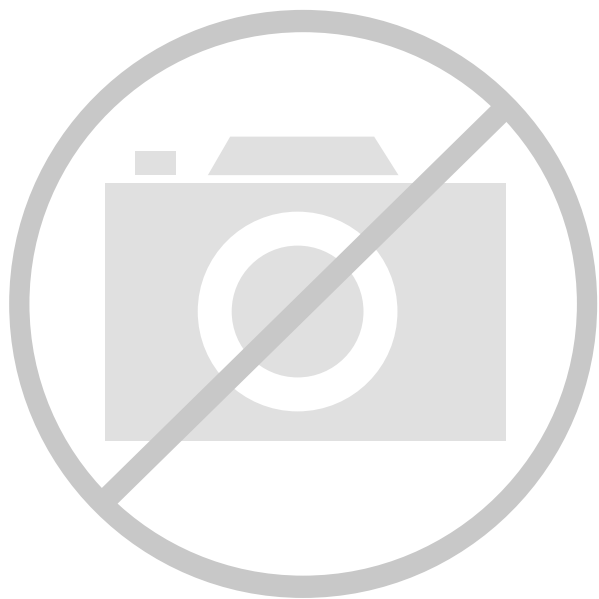




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	6144
Number of Logic Elements/Cells	27648
Total RAM Bits	393216
Number of I/O	404
Number of Gates	1569178
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	560-LBGA Exposed Pad, Metal
Supplier Device Package	560-MBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv1000e-7bg560c

Data Registers

The primary data register is the Boundary Scan register. For each IOB pin in the FPGA, bonded or not, it includes three bits for In, Out, and 3-State Control. Non-IOB pins have appropriate partial bit population if input-only or output-only. Each EXTEST CAPTURED-OR state captures all In, Out, and 3-state pins.

The other standard data register is the single flip-flop BYPASS register. It synchronizes data being passed through the FPGA to the next downstream Boundary Scan device.

The FPGA supports up to two additional internal scan chains that can be specified using the BSCAN macro. The macro provides two user pins (SEL1 and SEL2) which are decodes of the USER1 and USER2 instructions respectively. For these instructions, two corresponding pins (TDO1 and TDO2) allow user scan data to be shifted out of TDO.

Likewise, there are individual clock pins (DRCK1 and DRCK2) for each user register. There is a common input pin (TDI) and shared output pins that represent the state of the TAP controller (RESET, SHIFT, and UPDATE).

Bit Sequence

The order within each IOB is: In, Out, 3-State. The input-only pins contribute only the In bit to the Boundary Scan I/O data register, while the output-only pins contribute all three bits.

From a cavity-up view of the chip (as shown in EPIC), starting in the upper right chip corner, the Boundary Scan data-register bits are ordered as shown in [Figure 12](#).

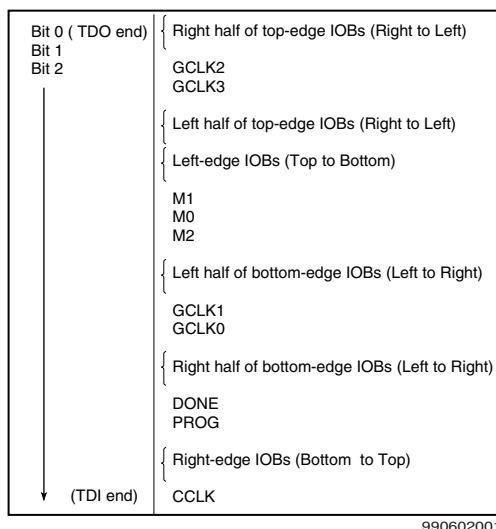


Figure 12: Boundary Scan Bit Sequence

BSDL (Boundary Scan Description Language) files for Virtex-E Series devices are available on the Xilinx web site in the File Download area.

Identification Registers

The IDCODE register is supported. By using the IDCODE, the device connected to the JTAG port can be determined.

The IDCODE register has the following binary format:

vvvv:ffff:ffa:aaaa:aaaa:cccc:cccc:ccc1

where

v = the die version number

f = the family code (05 for Virtex-E family)

a = the number of CLB rows (ranges from 16 for XCV50E to 104 for XCV3200E)

c = the company code (49h for Xilinx)

The USERCODE register is supported. By using the USERCODE, a user-programmable identification code can be loaded and shifted out for examination. The identification code (see [Table 7](#)) is embedded in the bitstream during bitstream generation and is valid only after configuration.

Table 7: IDCODEs Assigned to Virtex-E FPGAs

FPGA	IDCODE
XCV50E	v0A10093h
XCV100E	v0A14093h
XCV200E	v0A1C093h
XCV300E	v0A20093h
XCV400E	v0A28093h
XCV600E	v0A30093h
XCV1000E	v0A40093h
XCV1600E	v0A48093h
XCV2000E	v0A50093h
XCV2600E	v0A5C093h
XCV3200E	v0A68093h

Note:

Attempting to load an incorrect bitstream causes configuration to fail and can damage the device.

Including Boundary Scan in a Design

Since the Boundary Scan pins are dedicated, no special element needs to be added to the design unless an internal data register (USER1 or USER2) is desired.

If an internal data register is used, insert the Boundary Scan symbol and connect the necessary pins as appropriate.

the internal storage elements to begin changing state in response to the logic and the user clock.

The relative timing of these events can be changed. In addition, the GTS, GSR, and GWE events can be made depen-

Readback

The configuration data stored in the Virtex-E configuration memory can be readback for verification. Along with the configuration data it is possible to readback the contents all flip-flops/latches, LUT RAMs, and block RAMs. This capa-

Design Considerations

This section contains more detailed design information on the following features.

- Delay-Locked Loop . . . see [page 19](#)
- BlockRAM . . . see [page 24](#)
- SelectI/O . . . see [page 31](#)

Using DLLs

The Virtex-E FPGA series provides up to eight fully digital dedicated on-chip Delay-Locked Loop (DLL) circuits which provide zero propagation delay, low clock skew between output clock signals distributed throughout the device, and advanced clock domain control. These dedicated DLLs can be used to implement several circuits which improve and simplify system level design.

Introduction

As FPGAs grow in size, quality on-chip clock distribution becomes increasingly important. Clock skew and clock delay impact device performance and the task of managing clock skew and clock delay with conventional clock trees becomes more difficult in large devices. The Virtex-E series of devices resolve this potential problem by providing up to eight fully digital dedicated on-chip DLL circuits, which provide zero propagation delay and low clock skew between output clock signals distributed throughout the device.

Each DLL can drive up to two global clock routing networks within the device. The global clock distribution network minimizes clock skews due to loading differences. By monitoring a sample of the DLL output clock, the DLL can compensate for the delay on the routing network, effectively eliminating the delay from the external input port to the individual clock loads within the device.

In addition to providing zero delay with respect to a user source clock, the DLL can provide multiple phases of the source clock. The DLL can also act as a clock doubler or it can divide the user source clock by up to 16.

Clock multiplication gives the designer a number of design alternatives. For instance, a 50 MHz source clock doubled by the DLL can drive an FPGA design operating at 100 MHz. This technique can simplify board design because the clock path on the board no longer distributes such a

dent on the DONE pins of multiple devices all going High, forcing the devices to start synchronously. The sequence can also be paused at any stage until lock has been achieved on any or all DLLs.

bility is used for real-time debugging. For more detailed information, see application note XAPP138 "Virtex FPGA Series Configuration and Readback".

high-speed signal. A multiplied clock also provides designers the option of time-domain-multiplexing, using one circuit twice per clock cycle, consuming less area than two copies of the same circuit. Two DLLs in can be connected in series to increase the effective clock multiplication factor to four.

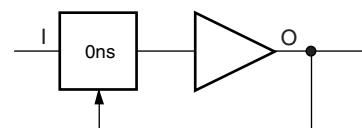
The DLL can also act as a clock mirror. By driving the DLL output off-chip and then back in again, the DLL can be used to deskew a board level clock between multiple devices.

In order to guarantee the system clock establishes prior to the device "waking up," the DLL can delay the completion of the device configuration process until after the DLL achieves lock.

By taking advantage of the DLL to remove on-chip clock delay, the designer can greatly simplify and improve system level design involving high-fanout, high-performance clocks.

Library DLL Symbols

Figure 21 shows the simplified Xilinx library DLL macro symbol, BUFGDLL. This macro delivers a quick and efficient way to provide a system clock with zero propagation delay throughout the device. **Figure 22** and **Figure 23** show the two library DLL primitives. These symbols provide access to the complete set of DLL features when implementing more complex applications.



ds022_25_121099

Figure 21: Simplified DLL Macro Symbol BUFGDLL

ground. As the DLL delay taps reset to zero, glitches can occur on the DLL clock output pins. Activation of the RST pin can also severely affect the duty cycle of the clock output pins. Furthermore, the DLL output clocks no longer deskew with respect to one another. For these reasons, rarely use the reset pin unless re-configuring the device or changing the input frequency.

2x Clock Output — CLK2X

The output pin CLK2X provides a frequency-doubled clock with an automatic 50/50 duty-cycle correction. Until the CLKDLL has achieved lock, the CLK2X output appears as a 1x version of the input clock with a 25/75 duty cycle. This behavior allows the DLL to lock on the correct edge with respect to source clock. This pin is not available on the CLKDLLHF primitive.

Clock Divide Output — CLKDV

The clock divide output pin CLKDV provides a lower frequency version of the source clock. The CLKDV_DIVIDE property controls CLKDV such that the source clock is divided by N where N is either 1.5, 2, 2.5, 3, 4, 5, 8, or 16.

This feature provides automatic duty cycle correction such that the CLKDV output pin always has a 50/50 duty cycle, with the exception of noninteger divides in HF mode, where the duty cycle is 1/3 for N=1.5 and 2/5 for N=2.5.

1x Clock Outputs — CLK[0/90/180/270]

The 1x clock output pin CLK0 represents a delay-compensated version of the source clock (CLKIN) signal. The CLKDLL primitive provides three phase-shifted versions of the CLK0 signal while CLKDLLHF provides only the 180 phase-shifted version. The relationship between phase shift and the corresponding period shift appears in Table 13.

Table 13: Relationship of Phase-Shifted Output Clock to Period Shift

Phase (degrees)	Period Shift (percent)
0	0%
90	25%
180	50%
270	75%

The timing diagrams in Figure 25 illustrate the DLL clock output characteristics.

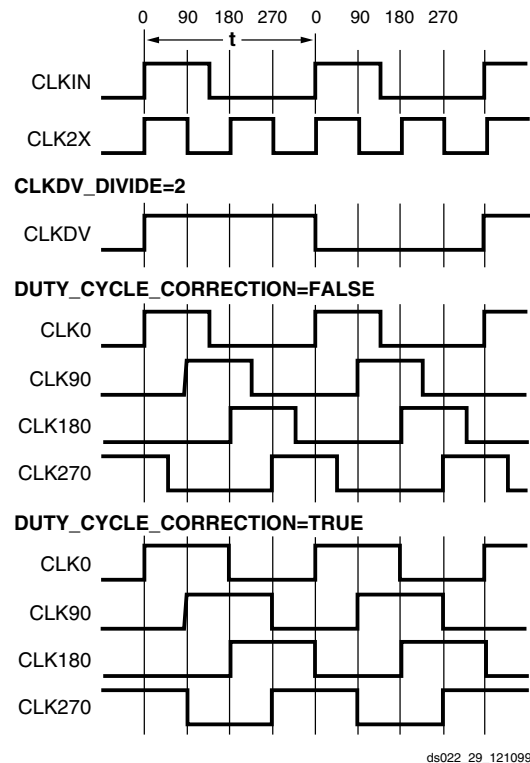


Figure 25: DLL Output Characteristics

The DLL provides duty cycle correction on all 1x clock outputs such that all 1x clock outputs by default have a 50/50 duty cycle. The DUTY_CYCLE_CORRECTION property (TRUE by default), controls this feature. In order to deactivate the DLL duty cycle correction, attach the DUTY_CYCLE_CORRECTION=FALSE property to the DLL symbol. When duty cycle correction deactivates, the output clock has the same duty cycle as the source clock.

The DLL clock outputs can drive an OBUF, a BUFG, or they can route directly to destination clock pins. The DLL clock outputs can only drive the BUFGs that reside on the same edge (top or bottom).

Locked Output — LOCKED

To achieve lock, the DLL might need to sample several thousand clock cycles. After the DLL achieves lock, the LOCKED signal activates. The DLL timing parameter section of the data sheet provides estimates for locking times.

To guarantee that the system clock is established prior to the device “waking up,” the DLL can delay the completion of the device configuration process until after the DLL locks. The STARTUP_WAIT property activates this feature.

Until the LOCKED signal activates, the DLL output clocks are not valid and can exhibit glitches, spikes, or other spurious movement. In particular the CLK2X output appears as a 1x clock with a 25/75 duty cycle.

standard requires a Differential Amplifier input buffer and a Push-Pull output buffer.

SSTL3 — Stub Series Terminated Logic for 3.3V

The Stub Series Terminated Logic for 3.3V, or SSTL3 standard is a general purpose 3.3V memory bus standard also sponsored by Hitachi and IBM (JESD8-8). This standard has two classes, I and II. SelectI/O devices support both classes for the SSTL3 standard. This standard requires a Differential Amplifier input buffer and an Push-Pull output buffer.

SSTL2 — Stub Series Terminated Logic for 2.5V

The Stub Series Terminated Logic for 2.5V, or SSTL2 standard is a general purpose 2.5V memory bus standard sponsored by Hitachi and IBM (JESD8-9). This standard has two classes, I and II. SelectI/O devices support both classes for the SSTL2 standard. This standard requires a Differential Amplifier input buffer and an Push-Pull output buffer.

CTT — Center Tap Terminated

The Center Tap Terminated, or CTT standard is a 3.3V memory bus standard sponsored by Fujitsu (JESD8-4). This standard requires a Differential Amplifier input buffer and a Push-Pull output buffer.

AGP-2X — Advanced Graphics Port

The Intel AGP standard is a 3.3V Advanced Graphics Port-2X bus standard used with the Pentium II processor for graphics applications. This standard requires a Push-Pull output buffer and a Differential Amplifier input buffer.

LVDS — Low Voltage Differential Signal

LVDS is a differential I/O standard. It requires that one data bit is carried through two signal lines. As with all differential signaling standards, LVDS has an inherent noise immunity over single-ended I/O standards. The voltage swing between two signal lines is approximately 350mV. The use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}) is not required. LVDS requires the use of two pins per input or output. LVDS requires external resistor termination.

BLVDS — Bus LVDS

This standard allows for bidirectional LVDS communication between two or more devices. The external resistor termination is different than the one for standard LVDS.

LVPECL — Low Voltage Positive Emitter Coupled Logic

LVPECL is another differential I/O standard. It requires two signal lines for transmitting one data bit. This standard specifies two pins per input or output. The voltage swing between these two signal lines is approximately 850 mV. The use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}) is not required. The LVPECL standard requires external resistor termination.

Library Symbols

The Xilinx library includes an extensive list of symbols designed to provide support for the variety of SelectI/O features. Most of these symbols represent variations of the five generic SelectI/O symbols.

- IBUF (input buffer)
- IBUFG (global clock input buffer)
- OBUF (output buffer)
- OBUFT (3-state output buffer)
- IOBUF (input/output buffer)

IBUF

Signals used as inputs to the Virtex-E device must source an input buffer (IBUF) via an external input port. The generic Virtex-E IBUF symbol appears in Figure 37. The extension

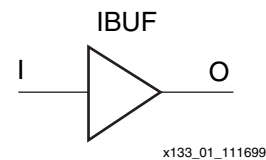


Figure 37: Input Buffer (IBUF) Symbols

to the base name defines which I/O standard the IBUF uses. The assumed standard is LVTTTL when the generic IBUF has no specified extension.

The following list details the variations of the IBUF symbol:

- IBUF
- IBUF_LVCMOS2
- IBUF_PCI33_3
- IBUF_PCI66_3
- IBUF_GTL
- IBUF_GTLP
- IBUF_HSTL_I
- IBUF_HSTL_III
- IBUF_HSTL_IV
- IBUF_SSTL3_I
- IBUF_SSTL3_II
- IBUF_SSTL2_I
- IBUF_SSTL2_II
- IBUF_CTT
- IBUF_AGP
- IBUF_LVCMOS18
- IBUF_LVDS
- IBUF_LVPECL

When the IBUF symbol supports an I/O standard that requires a V_{REF} , the IBUF automatically configures as a differential amplifier input buffer. The V_{REF} voltage must be supplied on the V_{REF} pins. In the case of LVDS, LVPECL, and BLVDS, V_{REF} is not required.

IOB Flip-Flop/Latch Property

The Virtex-E series I/O Block (IOB) includes an optional register on the input path, an optional register on the output path, and an optional register on the 3-state control pin. The design implementation software automatically takes advantage of these registers when the following option for the Map program is specified.

```
map -pr b <filename>
```

Alternatively, the IOB = TRUE property can be placed on a register to force the mapper to place the register in an IOB.

Location Constraints

Specify the location of each SelectI/O symbol with the location constraint LOC attached to the SelectI/O symbol. The external port identifier indicates the value of the location constrain. The format of the port identifier depends on the package chosen for the specific design.

The LOC properties use the following form:

```
LOC=A42
```

```
LOC=P37
```

Output Slew Rate Property

As mentioned above, a variety of symbol names provide the option of choosing the desired slew rate for the output buffers. In the case of the LVTTTL output buffers (OBUF, OBUFT, and IOBUF), slew rate control can be alternatively programmed with the SLEW= property. By default, the slew rate for each output buffer is reduced to minimize power bus transients when switching non-critical signals. The SLEW= property has one of the two following values.

```
SLEW=SLOW
```

```
SLEW=FAST
```

Output Drive Strength Property

The desired output drive strength can be additionally specified by choosing the appropriate library symbol. The Xilinx library also provides an alternative method for specifying this feature. For the LVTTTL output buffers (OBUF, OBUFT, and IOBUF), the desired drive strength can be specified with the DRIVE= property. This property could have one of the following seven values.

```
DRIVE=2
```

```
DRIVE=4
```

```
DRIVE=6
```

```
DRIVE=8
```

```
DRIVE=12 (Default)
```

```
DRIVE=16
```

```
DRIVE=24
```

Design Considerations

Reference Voltage (V_{REF}) Pins

Low-voltage I/O standards with a differential amplifier input buffer require an input reference voltage (V_{REF}). Provide the V_{REF} as an external signal to the device.

The voltage reference signal is “banked” within the device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See [Figure 38](#) for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

Within each V_{REF} bank, any input buffers that require a V_{REF} signal must be of the same type. Output buffers of any type and input buffers can be placed without requiring a reference voltage within the same V_{REF} bank.

Output Drive Source Voltage (V_{CCO}) Pins

Many of the low voltage I/O standards supported by SelectI/O devices require a different output drive source voltage (V_{CCO}). As a result each device can often have to support multiple output drive source voltages.

The Virtex-E series supports eight banks for the HQ and PQ packages. The CS package supports four V_{CCO} banks.

Output buffers within a given V_{CCO} bank must share the same output drive source voltage. Input buffers for LVTTTL, LVCMOS2, LVCMOS18, PCI33_3, and PCI 66_3 use the V_{CCO} voltage for Input V_{CCO} voltage.

Transmission Line Effects

The delay of an electrical signal along a wire is dominated by the rise and fall times when the signal travels a short distance. Transmission line delays vary with inductance and capacitance, but a well-designed board can experience delays of approximately 180 ps per inch.

Transmission line effects, or reflections, typically start at 1.5" for fast (1.5 ns) rise and fall times. Poor (or non-existent) termination or changes in the transmission line impedance cause these reflections and can cause additional delay in longer traces. As system speeds continue to increase, the effect of I/O delays can become a limiting factor and therefore transmission line termination becomes increasingly more important.

Termination Techniques

A variety of termination techniques reduce the impact of transmission line effects.

The following are output termination techniques:

- None
- Series
- Parallel (Shunt)
- Series and Parallel (Series-Shunt)

Date	Version	Revision
9/20/00	1.7	- Min values added to Virtex-E Electrical Characteristics tables. - XCV2600E and XCV3200E numbers added to Virtex-E Electrical Characteristics tables (Module 3). - Corrected user I/O count for XCV100E device in Table 1 (Module 1). - Changed several pins to “No Connect in the XCV100E” and removed duplicate V_{CCINT} pins in Table ~ (Module 4). - Changed pin J10 to “No connect in XCV600E” in Table 74 (Module 4). - Changed pin J30 to “VREF option only in the XCV600E” in Table 74 (Module 4). - Corrected pair 18 in Table 75 (Module 4) to be “AO in the XCV1000E, XCV1600E”.
11/20/00	1.8	- Upgraded speed grade -8 numbers in Virtex-E Electrical Characteristics tables to Preliminary. - Updated minimums in Table 13 and added notes to Table 14. - Added to note 2 to Absolute Maximum Ratings. - Changed speed grade -8 numbers for $T_{SHCKO32}$, T_{REG}, T_{BCCS}, and T_{ICKOF} - Changed all minimum hold times to –0.4 under Global Clock Set-Up and Hold for LVTTTL Standard, with DLL. - Revised maximum T_{DLLPW} in -6 speed grade for DLL Timing Parameters. - Changed GCLK0 to BA22 for FG860 package in Table 46.
2/12/01	1.9	- Revised footnote for Table 14. - Added numbers to Virtex-E Electrical Characteristics tables for XCV1000E and XCV2000E devices. - Updated Table 27 and Table 78 to include values for XCV400E and XCV600E devices. - Revised Table 62 to include pinout information for the XCV400E and XCV600E devices in the BG560 package. - Updated footnotes 1 and 2 for Table 76 to include XCV2600E and XCV3200E devices.
4/02/01	2.0	- Updated numerous values in Virtex-E Switching Characteristics tables. - Converted data sheet to modularized format. See the Virtex-E Data Sheet section.
4/19/01	2.1	Modified Figure 30 "DLL Generation of 4x Clock in Virtex-E Devices."
07/23/01	2.2	- Made minor edits to text under Configuration. - Added CLB column locations for XCV2600E and XCV3200E devices in Table 3.
11/09/01	2.3	Added warning under Configuration section that attempting to load an incorrect bitstream causes configuration to fail and can damage the device.
07/17/02	2.4	Data sheet designation upgraded from Preliminary to Production.
09/10/02	2.5	Added clarification to the Input/Output Block, Configuration, Boundary Scan Mode, and Block SelectRAM sections. Revised Figure 18, Table 11, and Table 36.
11/19/02	2.6	- Added clarification in the Boundary Scan section. - Removed last sentence regarding deactivation of duty-cycle correction in Duty Cycle Correction Property section.
06/15/04	2.6.1	Updated clickable web addresses.
01/12/06	2.7	Updated the Slave-Serial Mode and the Master-Serial Mode sections.
01/16/06	2.8	Made minor updates to Table 8.

IOB Input Switching Characteristics Standard Adjustments

			Speed Grade ⁽¹⁾				Units
Description	Symbol	Standard	Min	-8	-7	-6	
Data Input Delay Adjustments							
Standard-specific data input delay adjustments	T _{ILVTTL}	LVTTL	0.0	0.0	0.0	0.0	ns
	T _{ILVCMOS2}	LVC MOS2	−0.02	0.0	0.0	0.0	ns
	T _{ILVCMOS18}	LVC MOS18	0.12	+0.20	+0.20	+0.20	ns
	T _{ILVDS}	LVDS	0.00	+0.15	+0.15	+0.15	ns
	T _{ILVPECL}	LVPECL	0.00	+0.15	+0.15	+0.15	ns
	T _{IPCI33_3}	PCI, 33 MHz, 3.3 V	−0.05	+0.08	+0.08	+0.08	ns
	T _{IPCI66_3}	PCI, 66 MHz, 3.3 V	−0.05	−0.11	−0.11	−0.11	ns
	T _{IGTL}	GTL	+0.10	+0.14	+0.14	+0.14	ns
	T _{IGTLPLUS}	GTL+	+0.06	+0.14	+0.14	+0.14	ns
	T _{IHSTL}	HSTL	+0.02	+0.04	+0.04	+0.04	ns
	T _{ISSTL2}	SSTL2	−0.04	+0.04	+0.04	+0.04	ns
	T _{ISSTL3}	SSTL3	−0.02	+0.04	+0.04	+0.04	ns
	T _{ICTT}	CTT	+0.01	+0.10	+0.10	+0.10	ns
	T _{IAGP}	AGP	−0.03	+0.04	+0.04	+0.04	ns

Notes:

- Input timing t_i for LVTTL is measured at 1.4 V. For other I/O standards, see [Table 4](#).

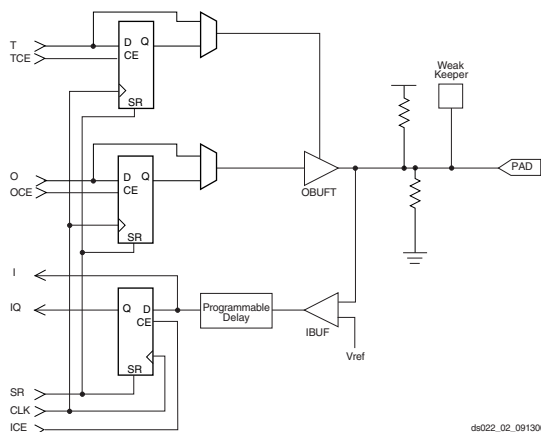


Figure 1: Virtex-E Input/Output Block (IOB)

Table 11: BG352 Differential Pin Pair Summary
XCV100E, XCV200E, XCV300E

Pair	Bank	P Pin	N Pin	AO	Other Functions
55	5	AC13	AD14	√	GCLK LVDS 1/0
56	5	AD15	AC15	√	VREF_5
57	5	AE16	AE17	√	-
58	5	AC16	AF18	2	-
59	5	AD17	AC17	√	-
60	5	AD18	AC18	√	VREF_5
61	5	AF20	AE20	1	-
62	5	AE21	AD20	√	VREF_5
63	5	AF23	AE22	√	-
64	5	AC21	AE23	√	VREF_5
65	6	AD25	AC24	√	-
66	6	AC26	AD26	√	VREF_6
67	6	AB25	AA24	√	-
68	6	Y24	AA25	√	VREF_6
69	6	W24	V23	2	-
70	6	U23	Y26	√	VREF_6
71	6	U24	V25	√	-
72	6	U25	T23	1	-
73	6	T26	T25	√	-
74	6	R25	R24	√	VREF_6
75	6	P24	R26	2	-
76	7	N24	N25	√	-
77	7	M24	M25	2	-
78	7	L26	M23	√	VREF_7
79	7	L24	K25	√	-
80	7	J25	J26	1	-
81	7	H25	K23	√	-
82	7	G26	J23	√	VREF_7
83	7	H24	G25	1	-
84	7	D26	G24	√	VREF_7
85	7	F24	E25	√	-
86	7	E24	D25	√	VREF_7

Notes:

1. AO in the XCV100E.
2. AO in the XCV200E.

BG432 Ball Grid Array Packages

XCV300E, XCV400E, and XCV600E devices in BG432 Ball Grid Array packages have footprint compatibility. Pins labeled IO_VREF can be used as either in all parts unless device-dependent as indicated in the footnotes. If the pin is not used as V_{REF} it can be used as general I/O. Immediately following Table 12, see Table 13 for Differential Pair information.

Table 12: BG432 — XCV300E, XCV400E, XCV600E

Bank	Pin Description	Pin #
0	GCK3	D17
0	IO	A22
0	IO	A26
0	IO	B20
0	IO	C23
0	IO	C28
0	IO_L0N_Y	B29
0	IO_L0P_Y	D27
0	IO_L1N_YY	B28
0	IO_L1P_YY	C27
0	IO_VREF_L2N_YY	D26
0	IO_L2P_YY	A28
0	IO_L3N_Y	B27
0	IO_L3P_Y	C26
0	IO_L4N_YY	D25
0	IO_L4P_YY	A27
0	IO_VREF_L5N_YY	D24
0	IO_L5P_YY	C25
0	IO_L6N_Y	B25
0	IO_L6P_Y	D23
0	IO_VREF_L7N_Y	C24 ¹
0	IO_L7P_Y	B24
0	IO_VREF_L8N_YY	D22
0	IO_L8P_YY	A24
0	IO_L9N_YY	C22
0	IO_L9P_YY	B22
0	IO_L10N_YY	C21
0	IO_L10P_YY	D20
0	IO_L11N_YY	B21
0	IO_L11P_YY	C20

Table 14: BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin#	See Note
4	IO_L104N_YY	AJ12	
4	IO_L105P_Y	AN11	
4	IO_L105N_Y	AK12	
4	IO_L106P_YY	AL12	
4	IO_L106N_YY	AM12	
4	IO_VREF_L107P_YY	AK13	3
4	IO_L107N_YY	AL13	
4	IO_L108P_Y	AM13	
4	IO_L108N_Y	AN13	
4	IO_L109P_YY	AJ14	
4	IO_L109N_YY	AK14	
4	IO_VREF_L110P_YY	AM14	
4	IO_L110N_YY	AN15	
4	IO_L111P_Y	AJ15	
4	IO_L111N_Y	AK15	
4	IO_L112P_Y	AL15	
4	IO_L112N_Y	AM16	
4	IO_VREF_L113P_Y	AL16	
4	IO_L113N_Y	AJ16	
4	IO_L114P_Y	AK16	
4	IO_VREF_L114N_Y	AN17	2
4	IO_LVDS_DLL_L115P	AM17	
5	GCK1	AJ17	
5	IO	AL25	
5	IO	AL28	
5	IO	AL30	
5	IO	AN28	
5	IO_LVDS_DLL_L115N	AM18	
5	IO_VREF	AL18	2
5	IO_L116P_Y	AK18	
5	IO_VREF_L116N_Y	AJ18	
5	IO_L117P_Y	AN19	
5	IO_L117N_Y	AL19	
5	IO_L118P_Y	AK19	

Table 14: BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin#	See Note
5	IO_L118N_Y	AM20	
5	IO_L119P_YY	AJ19	
5	IO_VREF_L119N_YY	AL20	
5	IO_L120P_YY	AN21	
5	IO_L120N_YY	AL21	
5	IO_L121P_Y	AJ20	
5	IO_L121N_Y	AM22	
5	IO_L122P_YY	AK21	
5	IO_VREF_L122N_YY	AN23	3
5	IO_L123P_YY	AJ21	
5	IO_L123N_YY	AM23	
5	IO_L124P_Y	AK22	
5	IO_L124N_Y	AM24	
5	IO_L125P_YY	AL23	
5	IO_L125N_YY	AJ22	
5	IO_L126P_YY	AK23	
5	IO_VREF_L126N_YY	AL24	
5	IO_L127P_Y	AN26	
5	IO_L127N_Y	AJ23	
5	IO_L128P_Y	AK24	
5	IO_VREF_L128N_Y	AM26	4
5	IO_L129P_Y	AM27	
5	IO_L129N_Y	AJ24	
5	IO_L130P_Y	AL26	
5	IO_VREF_L130N_Y	AK25	1
5	IO_L131P_YY	AN29	
5	IO_VREF_L131N_YY	AJ25	
5	IO_L132P_YY	AK26	
5	IO_L132N_YY	AM29	
5	IO_L133P_Y	AM30	
5	IO_L133N_Y	AJ26	
5	IO_L134P_YY	AK27	
5	IO_VREF_L134N_YY	AL29	
5	IO_L135P_YY	AN31	
5	IO_L135N_YY	AJ27	

Table 14: BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin#	See Note
NA	GND	A29	
NA	GND	A32	
NA	GND	A33	
NA	GND	B1	
NA	GND	B6	
NA	GND	B9	
NA	GND	B15	
NA	GND	B23	
NA	GND	B27	
NA	GND	B31	
NA	GND	C2	
NA	GND	E1	
NA	GND	F32	
NA	GND	G2	
NA	GND	G33	
NA	GND	J32	
NA	GND	K1	
NA	GND	L2	
NA	GND	M33	
NA	GND	P1	
NA	GND	P33	
NA	GND	R32	
NA	GND	T1	
NA	GND	V33	
NA	GND	W2	
NA	GND	Y1	
NA	GND	Y33	
NA	GND	AB1	
NA	GND	AC32	
NA	GND	AD33	
NA	GND	AE2	
NA	GND	AG1	
NA	GND	AG32	
NA	GND	AH2	
NA	GND	AJ33	

Table 14: BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin#	See Note
NA	GND	AL32	
NA	GND	AM3	
NA	GND	AM7	
NA	GND	AM11	
NA	GND	AM19	
NA	GND	AM25	
NA	GND	AM28	
NA	GND	AM33	
NA	GND	AN1	
NA	GND	AN2	
NA	GND	AN5	
NA	GND	AN10	
NA	GND	AN14	
NA	GND	AN16	
NA	GND	AN20	
NA	GND	AN22	
NA	GND	AN27	
NA	GND	AN33	

Notes:

1. V_{REF} or I/O option only in the XCV2000E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV1600E & 2000E; otherwise, I/O option only.
3. V_{REF} or I/O option only in the XCV1000E, 1600E, & 2000E; otherwise, I/O option only.
4. V_{REF} or I/O option only in the XCV600E, 1000E, 1600E, & 2000E; otherwise, I/O option only.

Table 21: FG676 Differential Pin Pair Summary
XCV400E, XCV600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
120	5	AD11	Y12	√	-
121	5	AB11	AD10	NA	-
122	5	AC11	AE10	√	-
123	5	AC10	AA11	√	-
124	5	Y11	AD9	1	-
125	5	AB10	AF9	√	-
126	5	AD8	AA10	√	VREF
127	5	AE8	Y10	√	-
128	5	AC9	AF8	1	VREF
129	5	AF7	AB9	1	-
130	5	AA9	AF6	√	-
131	5	AC8	AC7	√	VREF
132	5	AD6	Y9	√	-
133	5	AE5	AA8	√	-
134	5	AC6	AB8	√	VREF
135	5	AD5	AA7	√	-
136	5	AF4	AC5	2	-
137	6	AC3	AA5	√	-
138	6	AB4	AC2	√	-
139	6	AA4	W6	2	-
140	6	Y5	AB3	1	VREF
141	6	V7	AB2	1	-
142	6	Y4	AB1	√	-
143	6	W5	V5	√	VREF
144	6	V6	AA1	√	-
145	6	Y3	W4	2	-
146	6	U7	Y1	1	VREF
147	6	V4	W1	√	-
148	6	U6	W2	√	VREF
149	6	T5	V3	√	-
150	6	U4	U5	√	-
151	6	U3	T7	2	-
152	6	T6	U2	1	-
153	6	T4	U1	1	-

Table 21: FG676 Differential Pin Pair Summary
XCV400E, XCV600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
154	6	T3	R7	1	-
155	6	R6	R4	√	VREF
156	6	R5	R3	√	-
157	6	P7	P8	2	-
158	6	P6	R1	1	VREF
159	6	P4	P5	√	-
160	7	N8	N5	√	-
161	7	N3	N6	√	-
162	7	M2	N4	1	VREF
163	7	M7	N7	2	-
164	7	M3	M6	√	-
165	7	M5	M4	√	VREF
166	7	L7	L3	1	-
167	7	K2	L6	1	-
168	7	K1	L4	1	-
169	7	L5	K3	2	-
170	7	J3	K5	√	-
171	7	J4	K4	√	-
172	7	K6	H3	√	VREF
173	7	G3	K7	√	-
174	7	H1	J5	1	VREF
175	7	J6	G2	2	-
176	7	F1	J7	√	-
177	7	G4	H4	√	VREF
178	7	H5	F3	1	-
179	7	H6	E2	2	-
180	7	F4	G5	1	VREF
181	7	G6	H7	2	-
182	7	E4	E3	√	-

Notes:

1. AO in the XCV600E.
2. AO in the XCV400E.

Table 22: FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
2	IO_L63N	G4
2	IO_L64P	G3
2	IO_L64N	E2
2	IO_VREF_L65P_Y	H4
2	IO_L65N_Y	E1
2	IO_L66P_YY	H3
2	IO_L66N_YY	F2
2	IO_L67P	J4
2	IO_L67N	F1
2	IO_L68P_Y	J3
2	IO_L68N_Y	G2
2	IO_VREF_L69P_YY	G1
2	IO_L69N_YY	K4
2	IO_L70P_YY	H2
2	IO_L70N_YY	K3
2	IO_VREF_L71P	H1 ³
2	IO_L71N	L4
2	IO_L72P	J2
2	IO_L72N	L3
2	IO_VREF_L73P_YY	J1
2	IO_L73N_YY	M3
2	IO_L74P_YY	K2
2	IO_L74N_YY	N4
2	IO_L75P	K1
2	IO_L75N	N3
2	IO_VREF_L76P_YY	L2
2	IO_D1_L76N_YY	P4
2	IO_D2_L77P_YY	P3
2	IO_L77N_YY	L1
2	IO_L78P_Y	R4
2	IO_L78N_Y	M2
2	IO_L79P	R3
2	IO_L79N	M1
2	IO_L80P	T4
2	IO_L80N	N2
2	IO_VREF_L81P_Y	N1 ¹

Table 22: FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
2	IO_L81N_Y	T3
2	IO_L82P_YY	P2
2	IO_L82N_YY	U5
2	IO_L83P	P1
2	IO_L83N	U4
2	IO_L84P_Y	R2
2	IO_L84N_Y	U3
2	IO_VREF_L85P_YY	V5
2	IO_D3_L85N_YY	R1
2	IO_L86P_YY	V4
2	IO_L86N_YY	T2
2	IO_L87P	V3
2	IO_L87N	T1
2	IO_L88P	W4
2	IO_L88N	U2
2	IO_VREF_L89P_YY	W3
2	IO_L89N_YY	U1
2	IO_L90P_YY	AA3
2	IO_L90N_YY	V2
2	IO_VREF_L91P	AA4 ²
2	IO_L91N	V1
2	IO_L92P_YY	AB2
2	IO_L92N_YY	W2
3	IO	AP3
3	IO	AT3
3	IO	AB3
3	IO_L93P	AB4
3	IO_VREF_L93N	W1 ²
3	IO_L94P_YY	AB5
3	IO_L94N_YY	Y2
3	IO_L95P_YY	AC2
3	IO_VREF_L95N_YY	Y1
3	IO_L96P	AC3
3	IO_L96N	AA1
3	IO_L97P	AC4

FG680 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A ✓ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs that can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 23: FG680 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
GCLK LVDS					
3	0	A20	C22	NA	IO_DLL_L29N
2	1	D21	A19	NA	IO_DLL_L29P
1	5	AU22	AT22	NA	IO_DLL_L155N
0	4	AW19	AT21	NA	IO_DLL_L155P
IO LVDS					
Total Pairs: 247, Asynchronous Output Pairs: 111					
0	0	A36	C35	5	-
1	0	B35	D34	5	VREF
2	0	A35	C34	✓	-
3	0	B34	D33	✓	VREF
4	0	A34	C33	3	-
5	0	B33	D32	3	-
6	0	D31	C32	✓	-
7	0	C31	A33	✓	VREF
8	0	B31	B32	5	-
9	0	D30	A32	5	VREF
10	0	C30	A31	✓	-
11	0	D29	B30	✓	VREF
12	0	C29	A30	2	-
13	0	B29	A29	2	-
14	0	A28	B28	✓	VREF
15	0	B27	C28	✓	-
16	0	A27	D27	5	-
17	0	B26	C27	5	-

Table 23: FG680 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
18	0	C26	D26	✓	-
19	0	D25	A26	✓	VREF
20	0	C25	B25	3	-
21	0	D24	A25	3	-
22	0	B23	A24	✓	-
23	0	A23	C24	✓	VREF
24	0	B22	B24	5	-
25	0	A22	E23	5	-
26	0	B21	D23	✓	-
27	0	A21	C23	✓	VREF
28	0	B20	E22	2	-
29	1	A19	C22	NA	IO_LVDS_DLL
30	1	B19	C21	2	VREF
31	1	A18	C19	2	-
32	1	B18	D19	✓	VREF
33	1	A17	C18	✓	-
34	1	B17	D18	5	-
35	1	A16	E18	5	-
36	1	D17	C17	✓	VREF
37	1	E17	B16	✓	-
38	1	C16	A15	3	-
39	1	D16	B15	3	-
40	1	B14	A14	✓	VREF
41	1	A13	C15	✓	-
42	1	B13	D15	5	-
43	1	A12	C14	5	-
44	1	C13	D14	✓	-
45	1	D13	B12	✓	VREF
46	1	C12	A11	2	-
47	1	C11	B11	2	-
48	1	D11	A10	✓	VREF
49	1	C10	B10	✓	-
50	1	D10	A9	5	VREF
51	1	C9	B9	5	-

Table 23: FG680 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
120	3	AN4	AT1	4	-
121	3	AR2	AP4	4	VREF
122	3	AT2	AR3	6	-
123	3	AR4	AU2	√	INIT
124	4	AU4	AV5	√	-
125	4	AT6	AV4	5	-
126	4	AU6	AW4	5	VREF
127	4	AT7	AW5	√	-
128	4	AU7	AV6	√	VREF
129	4	AT8	AW6	3	-
130	4	AU8	AV7	3	-
131	4	AT9	AW7	√	-
132	4	AV8	AU9	√	VREF
133	4	AW8	AT10	5	-
134	4	AV9	AU10	5	VREF
135	4	AW9	AT11	√	-
136	4	AV10	AU11	√	VREF
137	4	AW10	AU12	2	-
138	4	AV11	AT13	2	-
139	4	AW11	AU13	√	VREF
140	4	AT14	AV12	√	-
141	4	AU14	AW12	5	-
142	4	AT15	AV13	5	-
143	4	AU15	AW13	√	-
144	4	AV14	AT16	√	VREF
145	4	AW14	AU16	3	-
146	4	AV15	AR17	3	-
147	4	AW15	AT17	√	-
148	4	AU17	AV16	√	VREF
149	4	AR18	AW16	5	-
150	4	AT18	AV17	5	-
151	4	AU18	AW17	√	-
152	4	AT19	AV18	√	VREF
153	4	AU19	AW18	2	-

Table 23: FG680 Differential Pin Pair Summary
XCV600E, XCV1000E, XCV1600E, XCV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
154	4	AU21	AV19	2	VREF
155	5	AT21	AT22	NA	IO_LVDS_DLL
156	5	AV20	AR22	8	VREF
157	5	AV23	AW21	√	VREF
158	5	AU23	AV21	√	-
159	5	AT23	AW22	5	-
160	5	AR23	AV22	5	-
161	5	AV24	AW23	√	VREF
162	5	AW24	AU24	√	-
163	5	AW25	AT24	3	-
164	5	AV25	AU25	3	-
165	5	AW26	AT25	√	VREF
166	5	AV26	AW27	√	-
167	5	AU26	AV27	5	-
168	5	AT26	AW28	5	-
169	5	AU27	AV28	√	-
170	5	AW29	AT27	√	VREF
171	5	AW30	AU28	2	-
172	5	AV30	AV29	2	-
173	5	AW31	AU29	√	VREF
174	5	AV31	AT29	√	-
175	5	AW32	AU30	5	VREF
176	5	AW33	AT30	5	-
177	5	AV33	AU31	√	VREF
178	5	AT31	AW34	√	-
179	5	AV32	AV34	3	-
180	5	AU32	AW35	3	-
181	5	AT32	AV35	√	VREF
182	5	AU33	AW36	√	-
183	5	AT33	AV36	5	VREF
184	5	AU34	AU36	5	-
185	6	AT38	AR36	√	-
186	6	AP36	AR38	6	-
187	6	AP37	AT39	4	VREF

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
2	IO_D1_L87N_YY	P2
2	IO_D2_L88P_YY	P3
2	IO_L88N_YY	L4
2	IO_L89P_Y	P1
2	IO_L89N_Y	R2
2	IO_L90P_Y	M5
2	IO_L90N_Y	R3
2	IO_L91P_Y	M4
2	IO_L91N_Y	R1
2	IO_L92P	N4
2	IO_L92N	T2
2	IO_L93P_Y	P5
2	IO_L93N_Y	T3
2	IO_VREF_L94P_Y	P4
2	IO_L94N_Y	T1
2	IO_L95P_YY	U2
2	IO_L95N_YY	R4
2	IO_L96P_Y	U3
2	IO_L96N_Y	T5
2	IO_L97P_Y	T4
2	IO_L97N_Y	V2
2	IO_VREF_L98P_YY	U5
2	IO_D3_L98N_YY	V3
2	IO_L99P_YY	V1
2	IO_L99N_YY	V5
2	IO_L100P_Y	W2
2	IO_L100N_Y	V4
2	IO_L101P_Y	W5
2	IO_L101N_Y	W1
2	IO_VREF_L102P_YY	Y2
2	IO_L102N_YY	W4
2	IO_L103P_YY	Y1
2	IO_L103N_YY	Y5
2	IO_VREF_L104P_Y	AA1 ¹
2	IO_L104N_Y	Y4
2	IO_L105P_YY	AA4
2	IO_L105N_YY	AA2

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
3	IO	AB4
3	IO	AC2
3	IO	AD1
3	IO	AE3
3	IO	AF4
3	IO	AH5
3	IO	AJ2
3	IO	AL1
3	IO	AM3
3	IO	AP3
3	IO	AR5
3	IO	AU4
3	IO	AB2
3	IO_L106P_Y	AB3
3	IO_VREF_L106N_Y	AC4 ¹
3	IO_L107P_YY	AB1
3	IO_L107N_YY	AC5
3	IO_L108P_YY	AD4
3	IO_VREF_L108N_YY	AC3
3	IO_L109P_Y	AC1
3	IO_L109N_Y	AD5
3	IO_L110P_Y	AE4
3	IO_L110N_Y	AD3
3	IO_L111P_YY	AE5
3	IO_L111N_YY	AD2
3	IO_D4_L112P_YY	AE1
3	IO_VREF_L112N_YY	AF5
3	IO_L113P_Y	AE2
3	IO_L113N_Y	AG4
3	IO_L114P_Y	AG5
3	IO_L114N_Y	AF1
3	IO_L115P_YY	AH4
3	IO_L115N_YY	AF2
3	IO_L116P_Y	AF3
3	IO_VREF_L116N_Y	AJ4
3	IO_L117P_Y	AG1

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
6	IO	AJ40
6	IO	AL41
6	IO	AN38
6	IO	AN42
6	IO	AP41
6	IO	AR39
6	IO_L211N_YY	AV41
6	IO_L211P_YY	AV42
6	IO_L212N_Y	AW40
6	IO_L212P_Y	AU41
6	IO_L213N_Y	AV39
6	IO_L213P_Y	AU42
6	IO_VREF_L214N_Y	AT41
6	IO_L214P_Y	AU38
6	IO_L215N	AT42
6	IO_L215P	AV40
6	IO_L216N_Y	AR41
6	IO_L216P_Y	AU39
6	IO_VREF_L217N_Y	AR42
6	IO_L217P_Y	AU40
6	IO_L218N_YY	AT38
6	IO_L218P_YY	AP42
6	IO_L219N_Y	AN41
6	IO_L219P_Y	AT39
6	IO_L220N_Y	AT40
6	IO_L220P_Y	AM40
6	IO_VREF_L221N_YY	AR38
6	IO_L221P_YY	AM41
6	IO_L222N_YY	AM42
6	IO_L222P_YY	AR40
6	IO_VREF_L223N_Y	AL40 ²
6	IO_L223P_Y	AP38
6	IO_L224N_Y	AP39
6	IO_L224P_Y	AL42
6	IO_VREF_L225N_YY	AP40
6	IO_L225P_YY	AK40
6	IO_L226N_YY	AK41

Table 24: FG860 — XCV1000E, XCV1600E, XCV2000E

Bank	Pin Description	Pin #
6	IO_L226P_YY	AN39
6	IO_L227N_Y	AK42
6	IO_L227P_Y	AN40
6	IO_VREF_L228N_YY	AM38
6	IO_L228P_YY	AJ41
6	IO_L229N_YY	AJ42
6	IO_L229P_YY	AM39
6	IO_L230N_Y	AH40
6	IO_L230P_Y	AH41
6	IO_L231N_Y	AL38
6	IO_L231P_Y	AH42
6	IO_L232N_Y	AL39
6	IO_L232P_Y	AG41
6	IO_L233N	AK39
6	IO_L233P	AG40
6	IO_L234N_Y	AJ38
6	IO_L234P_Y	AG42
6	IO_VREF_L235N_Y	AF42
6	IO_L235P_Y	AJ39
6	IO_L236N_YY	AF41
6	IO_L236P_YY	AH38
6	IO_L237N_Y	AE42
6	IO_L237P_Y	AH39
6	IO_L238N_Y	AG38
6	IO_L238P_Y	AE41
6	IO_VREF_L239N_YY	AG39
6	IO_L239P_YY	AD42
6	IO_L240N_YY	AD40
6	IO_L240P_YY	AF39
6	IO_L241N_Y	AD41
6	IO_L241P_Y	AE38
6	IO_L242N_Y	AE39
6	IO_L242P_Y	AC40
6	IO_VREF_L243N_YY	AD38
6	IO_L243P_YY	AC41
6	IO_L244N_YY	AB42
6	IO_L244P_YY	AC38

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
1	IO	J20 ⁵
1	IO	L18 ⁴
1	IO_LVDS_DLL_L34P	E16
1	IO_L35N_YY	B16
1	IO_VREF_L35P_YY	F16 ²
1	IO_L36N_YY	A16
1	IO_L36P_YY	H16
1	IO_L37N_YY	C16
1	IO_VREF_L37P_YY	K15
1	IO_L38N_YY	K16
1	IO_L38P_YY	G16
1	IO_L39N_Y	A17
1	IO_L39P_Y	E17
1	IO_L40N_Y	F17
1	IO_L40P_Y	C17
1	IO_L41N_YY	E18
1	IO_VREF_L41P_YY	A18
1	IO_L42N_YY	D18
1	IO_L42P_YY	A19
1	IO_L43N_Y	B19
1	IO_L43P_Y	G18
1	IO_L44N_Y	D19
1	IO_L44P_Y	H18
1	IO_L45N_YY	F18
1	IO_VREF_L45P_YY	F19 ¹
1	IO_L46N_YY	B20
1	IO_L46P_YY	K17
1	IO_L47N_Y	D20 ⁴
1	IO_L47P_Y	A20 ⁴
1	IO_L48N_Y	G19
1	IO_L48P_Y	C20
1	IO_L49N_Y	K18
1	IO_L49P_Y	E20
1	IO_L50N_YY	B21 ⁴
1	IO_L50P_YY	D21 ⁴
1	IO_L51N_YY	F20
1	IO_L51P_YY	A21

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
1	IO_L52N_YY	C21
1	IO_VREF_L52P_YY	A22
1	IO_L53N_YY	H19
1	IO_L53P_YY	B22
1	IO_L54N_YY	E21
1	IO_L54P_YY	D22
1	IO_L55N_YY	F21
1	IO_VREF_L55P_YY	C22
1	IO_L56N_YY	H20
1	IO_L56P_YY	E22
1	IO_L57N_Y	G21
1	IO_L57P_Y	A23
1	IO_L58N_Y	A24
1	IO_L58P_Y	K19
1	IO_L59N_YY	C24
1	IO_VREF_L59P_YY	B24
1	IO_L60N_YY	H21
1	IO_L60P_YY	G22
1	IO_L61N_Y	E23
1	IO_L61P_Y	C25
1	IO_L62N_Y	D24
1	IO_L62P_Y	A26
1	IO_L63N_YY	B26
1	IO_VREF_L63P_YY	K20
1	IO_L64N_YY	D25
1	IO_L64P_YY	J21
1	IO_L65N_Y	C26 ⁴
1	IO_L65P_Y	F23 ⁴
1	IO_L66N_Y	B27
1	IO_VREF_L66P_Y	G23 ¹
1	IO_L67N_Y	A27
1	IO_L67P_Y	F24
1	IO_L68N_YY	B28 ³
1	IO_L68P_YY	A28 ⁴
1	IO_WRITE_L69N_YY	K21
1	IO_CS_L69P_YY	C27

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
4	IO_L154N	AG23
4	IO_L155P_YY	AF22
4	IO_L155N_YY	AE22
4	IO_VREF_L156P_YY	AJ22
4	IO_L156N_YY	AG22
4	IO_L157P	AK24 ⁴
4	IO_L157N	AD20 ³
4	IO_L158P_YY	AA19
4	IO_L158N_YY	AF21
4	IO_L159P	AH22 ⁴
4	IO_VREF_L159N	AA18
4	IO_L160P	AG21
4	IO_L160N	AK23
4	IO_L161P_YY	AH21 ⁴
4	IO_L161N_YY	AD19 ⁴
4	IO_L162P	AE20
4	IO_L162N	AJ21
4	IO_L163P	AG20
4	IO_L163N	AF20
4	IO_L164P	AC18 ⁴
4	IO_L164N	AF19 ⁴
4	IO_L165P_YY	AJ20
4	IO_L165N_YY	AE19
4	IO_VREF_L166P_YY	AK22 ¹
4	IO_L166N_YY	AH20
4	IO_L167P	AG19
4	IO_L167N	AB17
4	IO_L168P	AJ19
4	IO_L168N	AD17
4	IO_L169P_YY	AA16
4	IO_L169N_YY	AA17
4	IO_VREF_L170P_YY	AK21
4	IO_L170N_YY	AB16
4	IO_L171P	AG18
4	IO_L171N	AK20
4	IO_L172P	AK19
4	IO_L172N	AD16

Table 26: FG900 — XCV600E, XCV1000E, XCV1600E

Bank	Pin Description	Pin #
4	IO_L173P_YY	AE16
4	IO_L173N_YY	AE17
4	IO_VREF_L174P_YY	AG17
4	IO_L174N_YY	AJ17
4	IO_L175P	AD15 ⁴
4	IO_L175N	AH17 ³
4	IO_VREF_L176P_YY	AG16 ²
4	IO_L176N_YY	AK17
4	IO_LVDS_DLL_L177P	AF16
5	GCK1	AK16
5	IO	AA11 ⁴
5	IO	AA14 ⁴
5	IO	AD14 ⁴
5	IO	AE7 ⁵
5	IO	AE8 ⁵
5	IO	AE10 ⁴
5	IO	AF6 ⁴
5	IO	AF10 ⁴
5	IO	AG9 ⁴
5	IO	AG12 ⁴
5	IO	AG14 ⁵
5	IO	AH8 ⁴
5	IO	AK6 ⁵
5	IO	AK14 ⁵
5	IO	AJ13 ⁴
5	IO	AJ15 ⁴
5	IO_LVDS_DLL_L177N	AH16
5	IO_L178P_YY	AC15 ⁴
5	IO_VREF_L178N_YY	AG15 ^{2,3}
5	IO_L179P_YY	AB15
5	IO_L179N_YY	AF15
5	IO_L180P_YY	AA15
5	IO_VREF_L180N_YY	AF14
5	IO_L181P_YY	AH15
5	IO_L181N_YY	AK15
5	IO_L182P	AB14

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
0	IO_L40P_Y	A17
0	IO_VREF_L41N_Y	G17 ¹
0	IO_L41P_Y	B17
0	IO_LVDS_DLL_L42N	C17
1	GCK2	D17
1	IO	A18
1	IO	B18 ³
1	IO	B24
1	IO	B25
1	IO	E22 ³
1	IO	E23 ³
1	IO	D18 ³
1	IO	D19
1	IO	D25 ³
1	IO	D26 ³
1	IO	D28 ³
1	IO	D29 ³
1	IO	G23 ³
1	IO	J23 ³
1	IO_LVDS_DLL_L42P	J18
1	IO_L43N_Y	G18
1	IO_VREF_L43P_Y	C18 ¹
1	IO_L44N_Y	H18
1	IO_L44P_Y	F18
1	IO_L45N_YY	B19
1	IO_VREF_L45P_YY	A19
1	IO_L46N_YY	K19
1	IO_L46P_YY	C19
1	IO_L47N	F19 ⁵
1	IO_L47P	E19 ⁴
1	IO_L48N_Y	G19
1	IO_L48P_Y	J19
1	IO_L49N_Y	A20

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
1	IO_L49P_Y	G20
1	IO_L50N	B20 ⁵
1	IO_L50P	F20 ⁴
1	IO_L51N_YY	D20
1	IO_VREF_L51P_YY	E20
1	IO_L52N_YY	H20
1	IO_L52P_YY	A21
1	IO_L53N	E21 ⁵
1	IO_L53P	J20 ⁴
1	IO_L54N_Y	D21
1	IO_L54P_Y	K20
1	IO_L55N_Y	B21
1	IO_L55P_Y	H21
1	IO_L56N_YY	G21 ⁵
1	IO_L56P_YY	F21 ⁴
1	IO_L57N_YY	A22
1	IO_VREF_L57P_YY	B22
1	IO_L58N_YY	J21
1	IO_L58P_YY	C22
1	IO_L59N_Y	D22
1	IO_L59P_Y	G22
1	IO_L60N_Y	K21
1	IO_L60P_Y	A23
1	IO_L61N_Y	F22
1	IO_L61P_Y	B23
1	IO_L62N_Y	C23
1	IO_L62P_Y	H22
1	IO_L63N_YY	D23
1	IO_L63P_YY	K22
1	IO_L64N_YY	A24
1	IO_VREF_L64P_YY	J22
1	IO_L65N_Y	H23
1	IO_L65P_Y	D24
1	IO_L66N_Y	A25

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
4	IO_L212N_YY	AP18
4	IO_L213P_Y	AF18
4	IO_L213N_Y	AP17
4	IO_VREF_L214P_Y	AJ18 ¹
4	IO_L214N_Y	AL18
4	IO_LVDS_DLL_L215P	AM18
5	GCK1	AL19
5	IO	AF17 ³
5	IO	AG12 ³
5	IO	AH12
5	IO	AJ10 ³
5	IO	AJ11 ³
5	IO	AK7 ³
5	IO	AK13 ³
5	IO	AL13 ³
5	IO	AM4 ³
5	IO	AN9
5	IO	AN10 ³
5	IO	AN16
5	IO	AN17 ³
5	IO_LVDS_DLL_L215N	AL17
5	IO_L216P_Y	AH17
5	IO_VREF_L216N_Y	AM17 ¹
5	IO_L217P_Y	AJ17
5	IO_L217N_Y	AG17
5	IO_L218P_YY	AP16
5	IO_VREF_L218N_YY	AL16
5	IO_L219P_YY	AJ16
5	IO_L219N_YY	AM16
5	IO_L220P	AK16 ⁵
5	IO_L220N	AP15 ⁴
5	IO_L221P_Y	AL15
5	IO_L221N_Y	AH16

Table 28: FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E

Bank	Pin Description	Pin #
5	IO_L222P_Y	AN15
5	IO_L222N_Y	AF16
5	IO_L223P_Y	AP14 ⁵
5	IO_L223N_Y	AE16 ⁴
5	IO_L224P_YY	AK15
5	IO_VREF_L224N_YY	AJ15
5	IO_L225P_YY	AH15
5	IO_L225N_YY	AN14
5	IO_L226P	AK14 ⁵
5	IO_L226N	AG15 ⁴
5	IO_L227P_Y	AM13
5	IO_L227N_Y	AF15
5	IO_L228P_Y	AG14
5	IO_L228N_Y	AP13
5	IO_L229P_YY	AE14 ⁵
5	IO_L229N_YY	AE15 ⁴
5	IO_L230P_YY	AN13
5	IO_VREF_L230N_YY	AG13
5	IO_L231P_YY	AH14
5	IO_L231N_YY	AP12
5	IO_L232P_Y	AJ14
5	IO_L232N_Y	AL14
5	IO_L233P_Y	AF13
5	IO_L233N_Y	AN12
5	IO_L234P_Y	AF14
5	IO_L234N_Y	AP11
5	IO_L235P_Y	AN11
5	IO_L235N_Y	AH13
5	IO_L236P_YY	AM12
5	IO_L236N_YY	AL12
5	IO_L237P_YY	AJ13
5	IO_VREF_L237N_YY	AP10
5	IO_L238P_Y	AK12
5	IO_L238N_Y	AM10